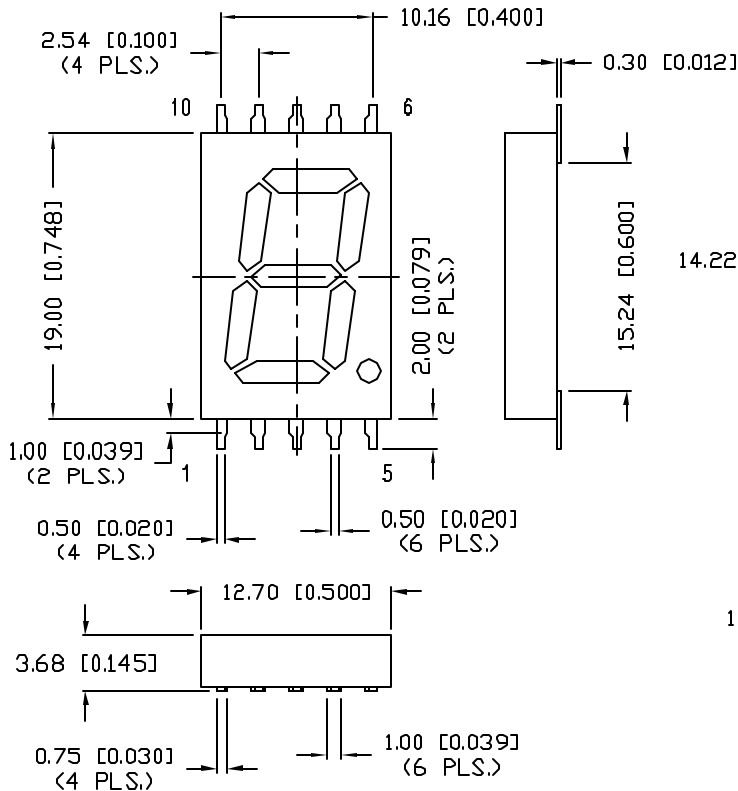
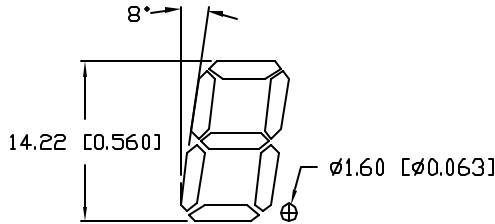


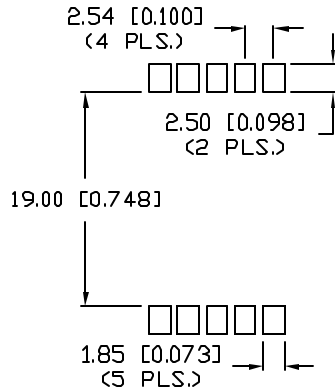
UNCONTROLLED DOCUMENT



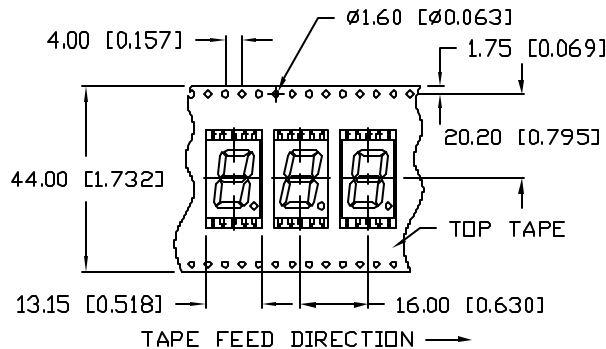
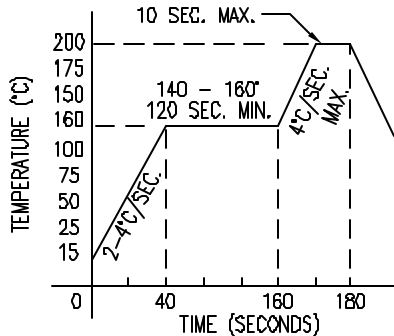
DIGIT DETAIL



RECOMMENDED SOLDER PAD LAYOUT



REFLOW PROFILE



PART NUMBER		REV.
LDS-SMC5602RD-TR		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10844.	3.21.02

ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565		nm	
FORWARD VOLTAGE		2.2	2.6	V <sub>f</sub>	
REVERSE VOLTAGE	5.0			V <sub>r</sub>	I <sub>f</sub> =100µA
AXIAL INTENSITY		1800		µcd	I <sub>f</sub> =10mA
EMITTED COLOR:	GREEN				
FACE COLOR:	BLACK				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

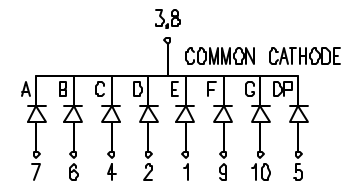
LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STeady CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

\* t<10µs

NOTES:

1. 1,000 PCS. PER REEL



REPLACES PART #: LDS-SMC5602RD

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN.=<sup>+DECIMAL PRECISION</sup><sub>-0.00</sub> MAX.=<sup>+0.00</sup><sub>-DECIMAL PRECISION</sub>

UNCONTROLLED DOCUMENT

REV. A	PART NUMBER LDS-SMC5602RD-TR	CONFIDENTIAL INFORMATION THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC, THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.	290 E. HELEN ROAD PALATINE, IL 60067-6976 PHONE: +1.847.359.2790 US WEB: www.lumex.com TW WEB: www.lumex.com.tw
0.56" SINGLE DIGIT SEVEN SEGMENT DISPLAY, SURFACE MOUNT, 565nm GREEN CHIPS, BLACK FACE, MILKY WHITE DIFFUSED.		RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.	DRAWN BY: [ ] CHECKED BY: [ ] APPROVED BY: [ ] DATE: 6.27.01 PAGE: 1 OF 1 SCALE: N/A